

Method for Bonding Substrates

Abstract

This invention relates to a method for bonding a first substrate (1) with a second substrate (2) by means of a connecting layer (7) that is arranged between the substrates (1, 2) and that consists of a connecting material (3, 5) with the following steps, in particular with the following sequence:

- Applying the connecting material (3, 5) to the first substrate (1) and/or the second substrate (2) in liquid form, and
- Distributing the connecting material (3, 5) between the substrates (1, 2) by bringing the substrates (1, 2) closer and as a result forming the shape of the connecting layer (7) with a thickness t .

In this regard, see Figure 1c.